

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (currently amended): For semiconductor manufacturing equipment, a ceramic susceptor ~~having in the surface or interior of its ceramic substrate a resistive heating element, the ceramic susceptor for semiconductor manufacturing equipment characterized in that its wafer carrying face in arched comprising:~~

~~contour when not heating is a concavity of 0.001 to 0.7 mm/300 mm a ceramic substrate;~~

~~a resistive heating element formed either superficially or interiorly in said ceramic substrate; and~~

~~a concavity molded in a wafer-carrying face defined on a surface of said ceramic substrate through which said resistive heating element issues heat when the susceptor performs a heating operation, said concavity being 0.001 to 0.7 mm/300 mm in negative arched contour when the susceptor is not heating.~~

Claim 2 (currently amended): A ~~semiconductor manufacturing equipment~~ ceramic susceptor as set forth in claim 1, ~~characterized in that wherein~~ the ceramic substrate is made of at least one ceramic selected from aluminum nitride, silicon nitride, aluminum oxynitride, and silicon carbide.

Claim 3 (currently amended): A ~~semiconductor manufacturing equipment~~ ceramic susceptor as set forth in claim 1 or 2, ~~characterized in that, wherein~~ the resistive heating element is made from at least one metal selected from tungsten, molybdenum, platinum, palladium, silver, nickel, and chrome.

Claim 4 (currently amended): A ~~semiconductor manufacturing equipment~~ ceramic susceptor as set forth in ~~any of claims 1 through 3, characterized in that claim 1, further~~

comprising a plasma electrode furthermore is disposed either in the surface or in the interior of the said ceramic substrate.

Claim 5 (new): A ceramic susceptor as set forth in claim 2, wherein the resistive heating element is made from at least one metal selected from tungsten, molybdenum, platinum, palladium, silver, nickel, and chrome.

Claim 6 (new): A ceramic susceptor as set forth in claim 2, further comprising a plasma electrode disposed either in the surface or in the interior of said ceramic substrate.

Claim 7 (new): A ceramic susceptor as set forth in claim 3, further comprising a plasma electrode disposed either in the surface or in the interior of said ceramic substrate.

Claim 8 (new): A ceramic susceptor as set forth in claim 5, further comprising a plasma electrode disposed either in the surface or in the interior of said ceramic substrate.